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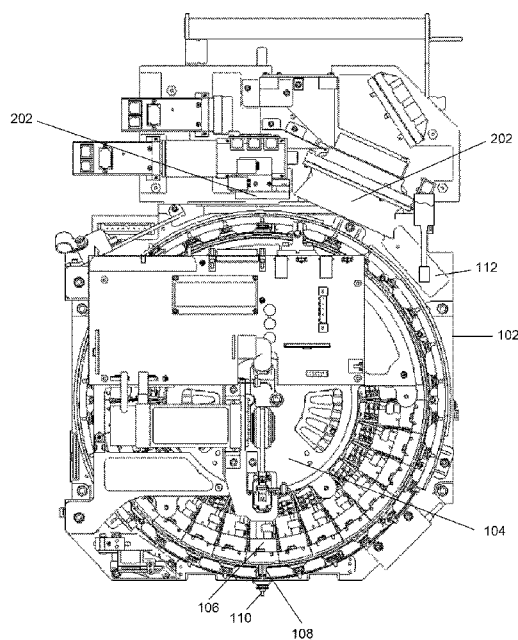


Figure 1

(57) Abstract: A component placement machine that includes a movable housing that is adapted for movement in an X and a Y axis above a printed circuit board. The housing includes a rotatable frame having at least one pick and place head configured to pick up a component and place the component on the printed circuit board. The housing further includes a fluid application station configured to apply fluid to the component after being picked up by the pick and place head and before being placed on the printed circuit board.